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(54) INTERCONNECTION ARRAY DEVICE WITH **SUPPORT**

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(57)**ABSTRACT**

It is described a interconnect array device (e.g., Ball Grid Array (BGA) device) comprising (a) a substrate having a substrate body and a main surface; (b) an array of solder connection elements formed at the main surface; and (c) a support structure formed at the main surface. The support structure is configured for maintaining, during a soldering process, a predefined spacing between the main surface of the substrate and a further main surface of a component carrier onto which the Ball Grid Array is mounted. The support structure comprises at least one support element. Further described is an electronic package with such a Ball Grid Array device and a method for manufacturing an electronic assembly comprising such an electronic package mounted on a component carrier.

